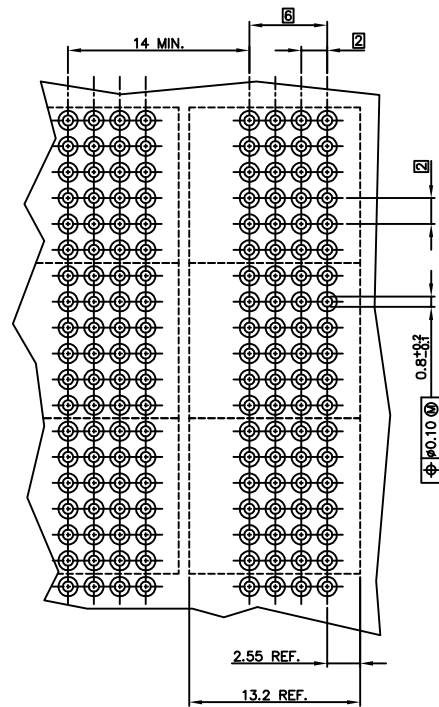
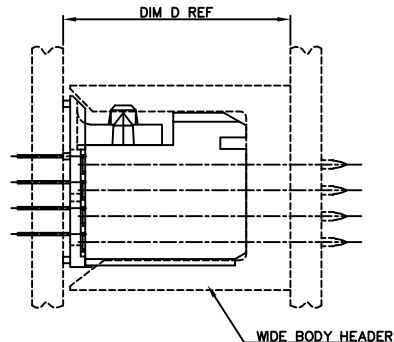
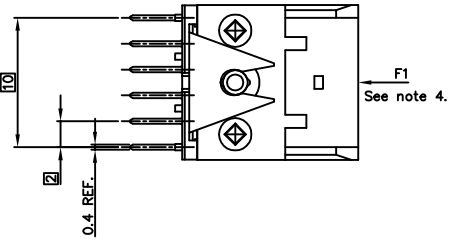
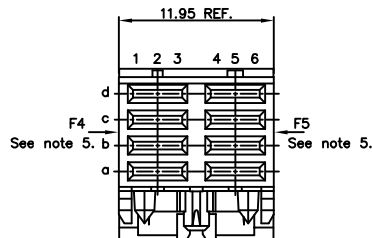
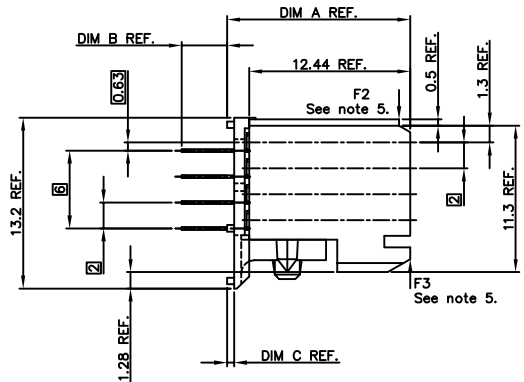


PRODUCT NR.	X	PLATING CONTACT AREA:	UNDERPLATING
85968-XYZ	1	0.8 μm GOLD	1.3 μm NI MIN.
85968-XYZLF	2	2 μm GOLD	1.3 μm NI MIN.
	3	1.3 μm GOLD	1.3 μm NI MIN.
	9	0.8 μm GXT	1.3 μm NI MIN.



RECOMMENDED HOLE PATTERN, COMPONENT SIDE.

DASH NR	CONFIGURATION						PCB THICKN.	DIM A	DIM B	DIM C	DIM D
	ROW #	COLUMN #									
-X01	D	+	+	+	+	+	2.4	14.14	3.50	0.54	17.64
	C	+	+	+	+	+					
	B	+	+	+	+	+					
-X01LF	A	+	+	+	+	+	3.2	13.60	4.04	0.00	17.10
	D	+	+	+	+	+					
	C	+	+	+	+	+					
-X02	B	+	+	+	+	+	2.4	13.60	3.24	0.00	17.10
	A	+	+	+	+	+					
	D	+	+	+	+	+					
-X02LF	C	+	+	+	+	+	1.6	13.60	2.39	0.00	17.10
	B	+	+	+	+	+					
	A	+	+	+	+	+					
-X03	D	+	+	+	+	+	1.6	14.14	2.70	0.54	17.64
	C	+	+	+	+	+					
	B	+	+	+	+	+					
-X03LF	A	+	+	+	+	+	1.6	14.64	3.00	0.54	18.14
	D	+	+	+	+	+					
	C	+	+	+	+	+					
-X04	B	+	+	+	+	+	1.6	15.14	2.50	0.54	18.64
	A	+	+	+	+	+					
	D	+	+	+	+	+					
-X04LF	C	+	+	+	+	+	1.6	15.14	2.50	0.54	18.64
	B	+	+	+	+	+					
	A	+	+	+	+	+					
-X05	D	+	+	+	+	+	1.6	15.14	2.50	0.54	18.64
	C	+	+	+	+	+					
	B	+	+	+	+	+					
-X05LF	A	+	+	+	+	+	1.6	15.14	2.50	0.54	18.64
	D	+	+	+	+	+					
	C	+	+	+	+	+					
-X06	B	+	+	+	+	+	1.6	15.14	2.50	0.54	18.64
	A	+	+	+	+	+					
	D	+	+	+	+	+					
-X06LF	C	+	+	+	+	+	1.6	15.14	2.50	0.54	18.64
	B	+	+	+	+	+					
	A	+	+	+	+	+					
-X07	D	+	+	+	+	+	1.6	15.14	2.50	0.54	18.64
	C	+	+	+	+	+					
	B	+	+	+	+	+					
-X07LF	A	+	+	+	+	+	1.6	15.14	2.50	0.54	18.64
	D	+	+	+	+	+					
	C	+	+	+	+	+					

"-" POSITION NOT LOADED
 "+" POSITION LOADED

NOTES:

- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
 FLAME RETARDANT ACC. UL 94-V0
- TERMINAL MATERIAL: PHOSPHOR BRONZE.
- PLATING SOLDER TAILS 2-8 μm SnPb 90-97 OR 2-8 μm PURE Sn FOR LF.
- LOAD IN THIS DIRECTION (E.G. THROUGH CODING) 30 NEWTON MAXIMUM PER CONNECTOR.
- LOAD IN THIS DIRECTION 15 NEWTON MAXIMUM PER CONNECTOR.
- TO ENSURE PROPER ALIGNMENT OF MULTIPLE MODULES ON A BOARD THE USE OF A FIXTURE IS RECOMMENDED.
- PRODUCT MARKING: PARTNUMBER & BATCH I.D.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

mat'l. code	tolerances unless otherwise specified	CUSTOMER COPY	FC ELECTRONICS
lit. ctrl. no. & date		projection	www.fcconnect.com
A 180221 MME 00016 linear		STR SIGN RCP	
B 180319 MME 00015		STB + WAFER 12mm	
C 172486 BRU 070720 020108		product family	NETRAL (cm) code
D 180303 PHE 00016 01 M. MEIER 000416	mm	size	dwg no. 213
E 0000-007 Clu 000412 0101 M. MEIER 000416	scale	5:1	sheet 1 of 1
F 0000-009 Clu 001018 0101 P. SCHALK 000416	sheet	A1	85968
G 1808-071 TER 0110/08/0101 P. SCHALK 000416	index	sheet	1